



Materials Declaration

Package	JLCC
Body Size	
Lead Count	28
Option	Au

Combolid			
Item	% of Combolid	Weight (g)	PPM
Kovar	92.00	9.20E-01	467219
Nickel	4.00	4.00E-02	20314
Gold	4.00	4.00E-02	20314
Subtotal		1.00E+00	507846

Lid Frame			
Item	% of Lid Frame	Weight (g)	PPM
Gold	79.58	1.03 E-02	5254
Sn	20.42	2.65 E-03	1348
Subtotal		1.30 E-02	6602

Ceramic Package			
Item	% of Ceramic	Weight (g)	PPM
Ceramic			
Al2O3	90.50	6.23 E-01	316205
SiO2	3.50	2.41 E-02	12229
CaO	0.60	4.13 E-03	2096
MgO	0.50	3.44 E-03	1747
TiO2	1.00	6.88 E-03	3494
Cr2O3	3.90	2.68 E-02	13627
Subtotal		6.88 E-01	349398

Pattern			
Item	% of Pattern	Weight (g)	PPM
Tungsten	91.61	3.09 E-02	15679
Molybdenum	8.31	2.80 E-03	1422
MgCO3	0.08	2.70 E-05	14
Subtotal		3.37 E-02	17114

Via Hole			
Item	% of Via Hole	Weight (g)	PPM
Molybdenum	83.30	2.17 E-04	110
Aluminum Oxide	16.70	4.34 E-05	22
Subtotal		2.60 E-04	132

Leads			
Item	% of Leads	Weight (g)	PPM
Iron	54.00	7.50 E-02	38064
Nickel	29.00	4.03 E-02	20442
Cobalt	17.00	2.36 E-02	11983
Subtotal		1.39 E-01	70489

Coating 1			
Item	% of Coating 1	Weight (g)	PPM
Ag	85.00	4.02 E-03	2042
Cu	15.00	7.10 E-04	360
Subtotal		4.73 E-03	2402

Coating 2			
Item	% of Coating 2	Weight (g)	PPM
Nickel	92.00	9.61 E-03	4882
Cobalt	8.00	8.36 E-04	425
Subtotal		1.05 E-02	5307
Total		8.76 E-01	444843

External Leadframe Plating			
Item	% of External Plating	Weight (g)	PPM
Gold	100.00	1.11 E-02	5617

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Aluminum	100.00	3.10 E-03	1574

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100.00	6.30 E-02	31994

Die Attach Paste			
Item	% of Die Attach Paste	Weight (g)	PPM
Silver Filler	80.00	2.40 E-03	1219
Cyanate ester resin	20.00	6.00 E-04	305
Subtotal		3.00 E-03	1524

Package Totals	
Weight (g)	PPM
1.97E+00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary





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Package	JLCC
Body Size	
Lead Count	28
Option	SnPb

Combolid			
Item	% of Combolid	Weight (g)	PPM
Kovar	92.00	9.20E-01	446797
Nickel	4.00	4.00E-02	19426
Gold	4.00	4.00E-02	19426
Subtotal		1.00E+00	485649

Lid Frame			
Item	% of Lid Frame	Weight (g)	PPM
Gold	79.58	1.03 E-02	5024
Sn	20.42	2.65 E-03	1289
Subtotal		1.30 E-02	6313

Ceramic Package			
Item	% of Ceramic	Weight (g)	PPM
Ceramic			
Al2O3	90.50	6.23 E-01	302385
SiO2	3.50	2.41 E-02	11694
CaO	0.60	4.13 E-03	2005
MgO	0.50	3.44 E-03	1671
TiO2	1.00	6.88 E-03	3341
Cr2O3	3.90	2.68 E-02	13031
Subtotal		6.88 E-01	334127
Pattern			
Tungsten	91.61	3.09 E-02	14993
Molybdenum	8.31	2.80 E-03	1360
MgCO3	0.08	2.70 E-05	13
Subtotal		3.37 E-02	16366
Via Hole			
Molybdenum	83.3	2.17 E-04	105
Aluminum Oxide	16.7	4.34 E-05	21
Subtotal		2.60 E-04	128
Leads			
Iron	54.00	7.50 E-02	36400
Nickel	29.00	4.03 E-02	19548
Cobalt	17.00	2.36 E-02	11459
Subtotal		1.39 E-01	67408
Coating 1			
Ag	85.00	4.02 E-03	1953
Cu	15.00	7.10 E-04	345
Subtotal		4.73 E-03	2297
Coating 2			
Nickel	92.00	9.61 E-03	4669
Cobalt	8.00	8.36 E-04	406
Subtotal		1.05 E-02	5075
Coating 3			
Gold	100.00	1.11 E-02	5371
Total		8.87 E-01	430771

External Leadframe Plating			
Item	% of External Plating	Weight (g)	PPM
Sn	63.00	5.67 E-02	27536
Pb	37.00	3.33 E-02	16172
Subtotal		9.00 E-02	43708

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Aluminum	100.00	3.10 E-03	1506

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100.00	6.30 E-02	30596

Die Attach Paste			
Item	% of Die Attach Paste	Weight (g)	PPM
Silver Filler	80.00	2.40 E-03	1166
Cyanate ester resin	20.00	6.00 E-04	291
		3.00 E-03	1457

Package Totals	
Weight (g)	PPM
2.06E+00	1000000

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